

# C4D08120E **Silicon Carbide Schottky Diode**

# Z-Rec® Rectifier

 $\mathbf{V}_{\text{RRM}}$ 1200 V  $I_{r}(T_{c}=135^{\circ}C) = 12 A$ 37 nC Q<sub>c</sub>

#### **Features**

- 1.2kV Schottky Rectifier
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching
- Extremely Fast Switching
- Positive Temperature Coefficient on V<sub>F</sub>

## **Benefits**

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Reduction of Heat Sink Requirements



Parallel Devices Without Thermal Runaway

# **Applications**

- Solar Inverters
- **UPS**
- **Motor Drives**
- **Power Factor Correction**



**Package** 

TO-252-2

Part Number	Package	Marking	
C4D08120E	TO-252-2	C4D08120	

Halogen-Free

## **Maximum Ratings** (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1200	V		
V <sub>RSM</sub>	Surge Peak Reverse Voltage	1300	V		
V <sub>DC</sub>	DC Blocking Voltage	1200	V		
I <sub>F</sub>	Continuous Forward Current	24.5 12 8	А	T <sub>c</sub> =25°C T <sub>c</sub> =135°C T <sub>c</sub> =155°C	
$\mathbf{I}_{FRM}$	Repetitive Peak Forward Surge Current	38 26	А	$T_c$ =25°C, $t_p$ =10 ms, Half Sine pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine pulse	
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current	64 50	А	$T_c$ =25°C, $t_p$ =10 ms, Half Sine pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine pulse	
${ m I}_{ m F,Max}$	Non-Repetitive Peak Forward Current	600 480	А	$T_c$ =25°C, $t_p$ =10 $\mu$ s, Pulse $T_c$ =110°C, $t_p$ =10 $\mu$ s, Pulse	
P <sub>tot</sub>	Power Dissipation	137 59	W	T <sub>c</sub> =25°C T <sub>c</sub> =110°C	
T,	Operating Junction Range	-55 to +175	°C		
T <sub>stg</sub>	Storage Temperature Range	-55 to +135	°C		



### **Electrical Characteristics**

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V <sub>F</sub>	Forward Voltage	1.5 2.2	1.8 3	V	$I_F = 2 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 2 \text{ A } T_J = 175^{\circ}\text{C}$	
I <sub>R</sub>	Reverse Current	35 100	250 350	μΑ	V <sub>R</sub> = 1200 V T <sub>J</sub> =25°C V <sub>R</sub> = 1200 V T <sub>J</sub> =175°C	
Q <sub>c</sub>	Total Capacitive Charge	37		nC	$V_R = 800 \text{ V, } I_F = 2A$ $di/dt = 200 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	
С	Total Capacitance	560 37 27		pF	$V_R = 0 \text{ V}, T_J = 25^{\circ}\text{C}, f = 1 \text{ MHz}$ $V_R = 400 \text{ V}, T_J = 25^{\circ}\text{C}, f = 1 \text{ MHz}$ $V_R = 800 \text{ V}, T_J = 25^{\circ}\text{C}, f = 1 \text{ MHz}$	

#### Note:

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Unit
$R_{_{ heta JC}}$	TO-252 Package Thermal Resistance from Junction to Case	1.1	°C/W

# **Typical Performance**

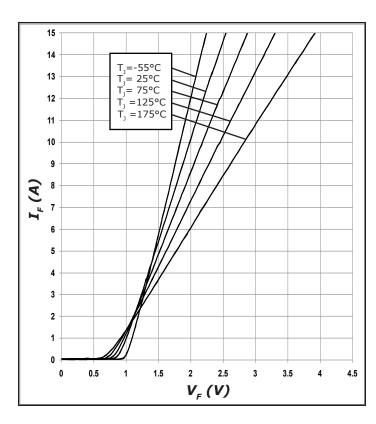


Figure 1. Forward Characteristics

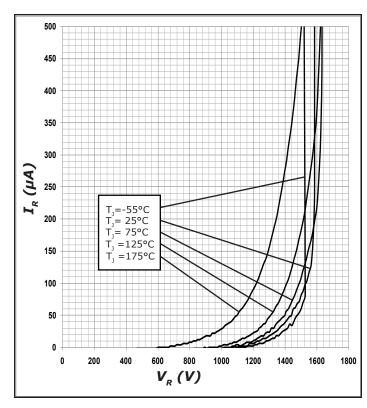
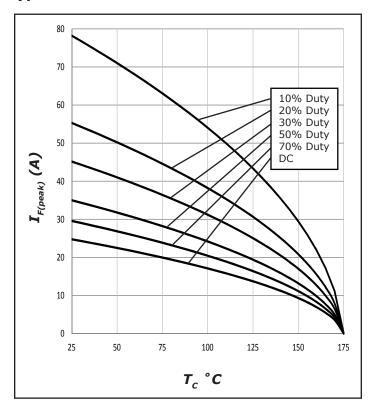


Figure 2. Reverse Characteristics

<sup>1.</sup> This is a majority carrier diode, so there is no reverse recovery charge.



# **Typical Performance**



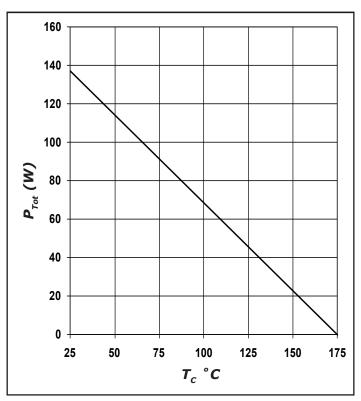


Figure 3. Current Derating

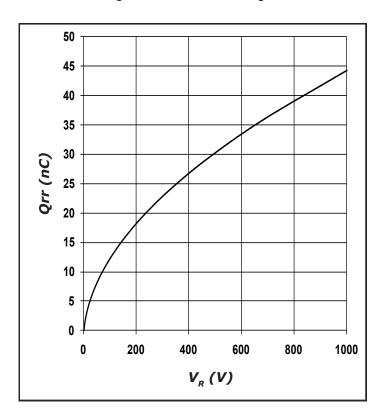


Figure 5. Recovery Charge vs. Reverse Voltage

Figure 4. Power Derating

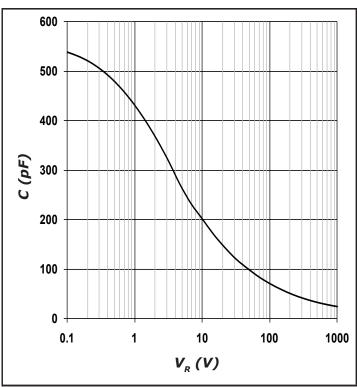


Figure 6. Capacitance vs. Reverse Voltage



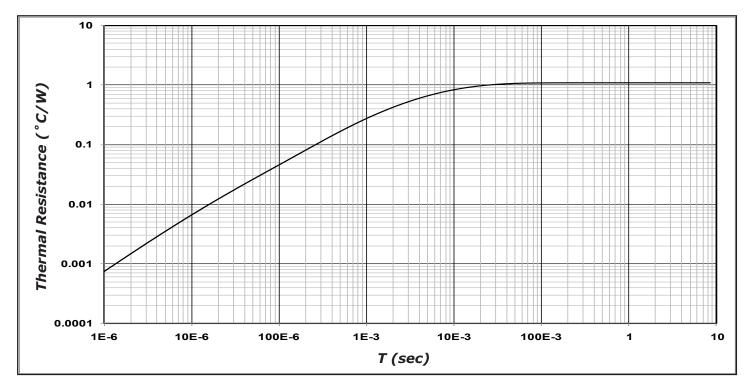


Figure 7. Transient Thermal Impedance

### **Diode Model**

$$\begin{array}{c|c} - & & \\ \hline V_T & R_T \end{array}$$

$$V_{fT} = V_T + If^*R_T$$

$$V_T = 0.96 + (T_J^* - 2.1^*10^{-3})$$

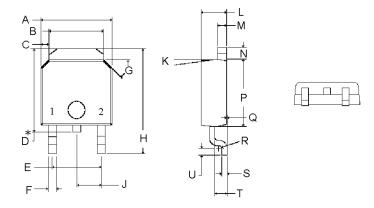
$$R_T = 0.06 + (T_J^* 8.0^*10^{-4})$$

Note:  $T_j$  = Diode Junction Temperature In Degrees Celsius, valid from 25°C to 175°C



# **Package Dimensions**

Package TO-252-2

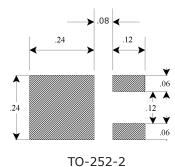




POS	Inc	hes	Millimeters		
PUS	Min	Max	Min	Max	
А	.250	.289	6.350	7.341	
В	.197	.215	5.004	5.461	
С	.027	.050	.686	1.270	
D*	.270	.322	6.858	8.179	
Е	.178	.182	4.521	4.623	
F	.025	.045	.635	1.143	
G	44°	46°	44°	46°	
Н	.380	.410	9.652	10.414	
J	.090	.090 TYP		2.286 TYP	
K	6°	8°	6°	8°	
L	.086	.094	2.184	2.388	
М	.018	.034	.457	.864	
N	.035	.050	.889	1.270	
Р	.231	.246	5.867	6.248	
Q	0.00	.005	0.00	.127	
R	R0.010 TYP		R0.254 TYP		
S	.017	.023	.432	.584	
Т	.038	.045	.965	1.143	
U	.021	.029	.533	.737	

Note:

# **Recommended Solder Pad Layout**



Part Number	Package	Marking
C4D05120E	TO-252-2	C4D05120

Note: Recommended soldering profiles can be found in the applications note here: http://www.cree.com/power\_app\_notes/soldering



<sup>\*</sup> Tab "D" may not be present



#### **Notes**

#### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

#### REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

• This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.